

Resource Summary Report

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Oxford: PlasmaPro 80 RIE Plasma Technology

RRID:SCR_020381

Type: Tool

Proper Citation

Oxford: PlasmaPro 80 RIE Plasma Technology (RRID:SCR_020381)

Resource Information

URL: <https://plasma.oxinst.com/products/rie/80rie>

Proper Citation: Oxford: PlasmaPro 80 RIE Plasma Technology (RRID:SCR_020381)

Description: PlasmaPro 80 reactive ion etch is compact, small footprint system offering etch and deposition solutions with open loading. Open load design allows fast wafer loading and unloading, ideal for research, prototyping and low volume production. It enables high performance processes using optimised electrode cooling and substrate temperature control.

Resource Type: instrument resource

Keywords: Oxford, Plasma Technology, Instrument, Resource equipment, Equipment, USEDit,

Availability: Commercially available

Resource Name: Oxford: PlasmaPro 80 RIE Plasma Technology

Resource ID: SCR_020381

Alternate IDs: Model_Number_80_RIE

Record Creation Time: 20220129T080350+0000

Record Last Update: 20260829T182653+0000

Ratings and Alerts

No rating or validation information has been found for Oxford: PlasmaPro 80 RIE Plasma Technology.

No alerts have been found for Oxford: PlasmaPro 80 RIE Plasma Technology.

Data and Source Information

Source: [SciCrunch Registry](#)

Usage and Citation Metrics

We have not found any literature mentions for this resource.